



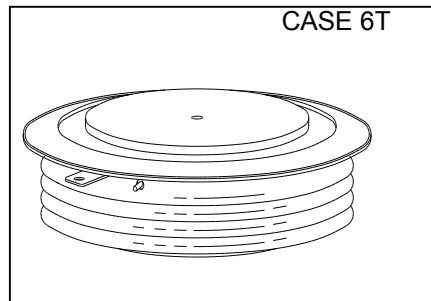
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Runau Electronics(Yangzhou)Manufacturing Co.,Ltd 1200 - 2100 V<sub>DRM</sub>; 3925A rms**YC781- Power Thyristor****HIGH POWER THYRISTOR FOR PHASE CONTROL APPLICATIONS****Features:**

- . All Diffused Structure
- . Interdigitated Amplifying Gate Configuration
- . Blocking capability up to 2100 volts
- . Guaranteed Maximum Turn-Off Time
- . High dV/dt Capability
- . Pressure Assembled Device

**ELECTRICAL CHARACTERISTICS AND RATINGS****Blocking - Off State**

Device Type	V <sub>RRM</sub> (1)	V <sub>DRM</sub> (1)	V <sub>RSM</sub> (1)
YC781PB	1200	1200	1300
YC781PD	1400	1400	1500
YC781PE	1500	1500	1600
YC781PM	1600	1600	1700
YC781PS	1700	1700	1800
YC781PN	1800	1800	1900
YC781L	2000	2000	2100
YC781LA	2100	2100	2200

V<sub>RRM</sub> = Repetitive peak reverse voltageV<sub>DRM</sub> = Repetitive peak off state voltageV<sub>RSM</sub> = Non repetitive peak reverse voltage (2)

## Notes:

All ratings are specified for T<sub>j</sub>=25 °C unless otherwise stated.

(1) All voltage ratings are specified for an applied 50Hz/60Hz sinusoidal waveform over the temperature range -40 to +125 °C.

(2) 10 msec. max. pulse width

(3) Maximum value for T<sub>j</sub> = 125 °C.

(4) Minimum value for linear and exponential waveshape to 80% rated V<sub>DRM</sub>. Gate open. T<sub>j</sub> = 125 °C.

(5) Non-repetitive value.

(6) The value of di/dt is established in accordance with EIA/NIMA Standard RS-397, Section 5-2-2-6. The value defined would be in addition to that obtained from a snubber circuit, comprising a 0.2 µF capacitor and 20 ohms resistance in parallel with the thristor under test.

Repetitive peak reverse leakage and off state leakage	I <sub>RRM</sub> / I <sub>DRM</sub>	10 mA 150 mA (3)
Critical rate of voltage rise	dV/dt (4)	500 V/µsec

**Conducting - on state**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Average value of on-state current	I <sub>T(AV)</sub>		2500		A	Sinewave,180° conduction,T <sub>c</sub> =72°C
RMS value of on-state current	I <sub>TRMS</sub>		3925		A	Nominal value
Peak one cycle surge (non repetitive) current	I <sub>TSM</sub>		45000 41500		A A	8.3 msec (60Hz), sinusoidal wave- shape, 180° conduction, T <sub>j</sub> = 125 °C 10.0 msec (50Hz), sinusoidal wave- shape, 180° conduction, T <sub>j</sub> = 125 °C
I square t	I <sup>2</sup> t		8.5x10 <sup>6</sup>		A <sup>2</sup> s	8.3 msec
Latching current	I <sub>L</sub>		400		mA	V <sub>D</sub> = 24 V; R <sub>L</sub> = 12 ohms
Holding current	I <sub>H</sub>		100		mA	V <sub>D</sub> = 24 V; I = 2.5 A
Peak on-state voltage	V <sub>TM</sub>		1.2		V	I <sub>TM</sub> = 2000 A; T <sub>j</sub> = 125 °C
Critical rate of rise of on-state current (5, 6)	di/dt		300		A/µs	Switching from V <sub>DRM</sub> ≤ 1500 V, non-repetitive
Critical rate of rise of on-state current (6)	di/dt		100		A/µs	Switching from V <sub>DRM</sub> ≤ 1500 V

**Gating**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Peak gate power dissipation	P <sub>GM</sub>		200		W	t <sub>p</sub> = 40 us
Average gate power dissipation	P <sub>G(AV)</sub>		5		W	
Peak gate current	I <sub>GM</sub>		15		A	
Gate current required to trigger all units	I <sub>GT</sub>		300 200 125		mA	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = -40 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = +25 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = +125 °C
Gate voltage required to trigger all units	V <sub>GT</sub>	0.30	5 4		V	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = -40 °C V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = 0-125 °C V <sub>D</sub> = Rated V <sub>DRM</sub> ; R <sub>L</sub> = 1000 ohms; T <sub>j</sub> = + 125 °C
Peak negative voltage	V <sub>GRM</sub>		15		V	

**Dynamic**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t <sub>d</sub>		3.0	2.5	μs	I <sub>TM</sub> = 50 A; V <sub>D</sub> = 67% V <sub>DRM</sub> Gate pulse: V <sub>G</sub> = 30 V; R <sub>G</sub> = 10 ohms; t <sub>r</sub> = 0.1 μs; t <sub>p</sub> = 20 μs
Turn-off time (with V <sub>R</sub> = -5 V)	t <sub>q</sub>		400	250	μs	I <sub>TM</sub> > 2000 A; di/dt = 25 A/μs; V <sub>R</sub> ≥ -5 V; Re-applied dV/dt = 400 V/μs linear to 67% V <sub>DRM</sub> ; T <sub>j</sub> = 125 °C; Duty cycle ≥ 0.01%
Reverse recovery current	I <sub>rr</sub>		200		A	I <sub>TM</sub> > 2000 A; di/dt = 25 A/μs; V <sub>R</sub> ≥ -50 V; T <sub>j</sub> = 125 °C

**THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T <sub>j</sub>	-40	+125		°C	
Storage temperature	T <sub>stg</sub>	-40	+150		°C	
Thermal resistance - junction to case	R <sub>θ(j-c)</sub>		0.012		°C/W	Double sided cooled
Thermal resistamce - case to sink	R <sub>θ(c-s)</sub>		0.001		°C/W	Double sided cooled *
Mounting force	P	8000 35.5	10000 44.4		lb. kN	
Weight	W			3.5 1.60	Lb. Kg.	

\* Mounting surfaces smooth, flat and greased

